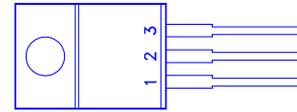
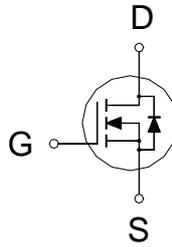


PRODUCT SUMMARY

$V_{(BR)DSS}$	$R_{DS(ON)}$	I_D
75	8mΩ	89A



1. GATE
2. DRAIN
3. SOURCE

ABSOLUTE MAXIMUM RATINGS ($T_A = 25\text{ °C}$ Unless Otherwise Noted)

PARAMETERS/TEST CONDITIONS		SYMBOL	LIMITS	UNITS
Gate-Source Voltage		V_{GS}	±20	V
Continuous Drain Current ¹	$T_C = 25\text{ °C}$	I_D	89	A
	$T_C = 100\text{ °C}$		63	
Pulsed Drain Current ²		I_{DM}	250	
Avalanche Current		I_{AS}	85	
Avalanche Energy	L = 0.1mH	E_{AS}	362	mJ
Power Dissipation	$T_C = 25\text{ °C}$	P_D	160	W
	$T_C = 100\text{ °C}$		80	
Operating Junction & Storage Temperature Range		T_j, T_{stg}	-55 to 175	°C

THERMAL RESISTANCE RATINGS

THERMAL RESISTANCE	SYMBOL	TYPICAL	MAXIMUM	UNITS
Junction-to-Case	$R_{\theta JC}$		0.94	°C / W
Case-to-Heatsink	$R_{\theta CS}$	0.5		

¹Pulse width limited by maximum junction temperature.

²Limited by package.

ELECTRICAL CHARACTERISTICS ($T_J = 25\text{ °C}$, Unless Otherwise Noted)

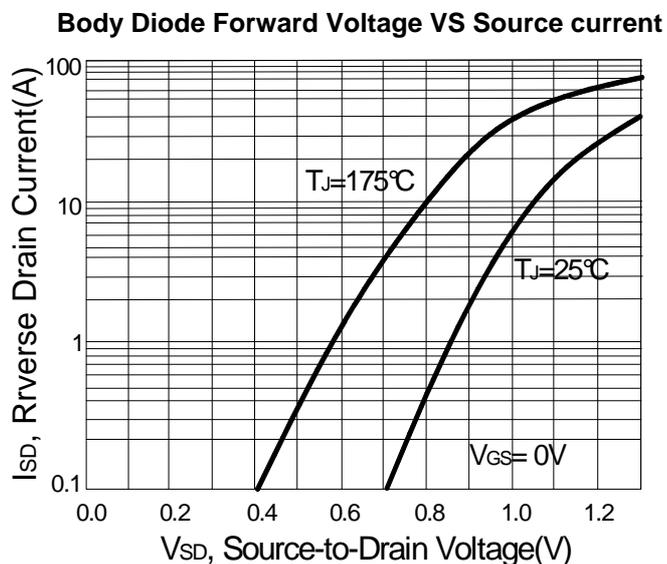
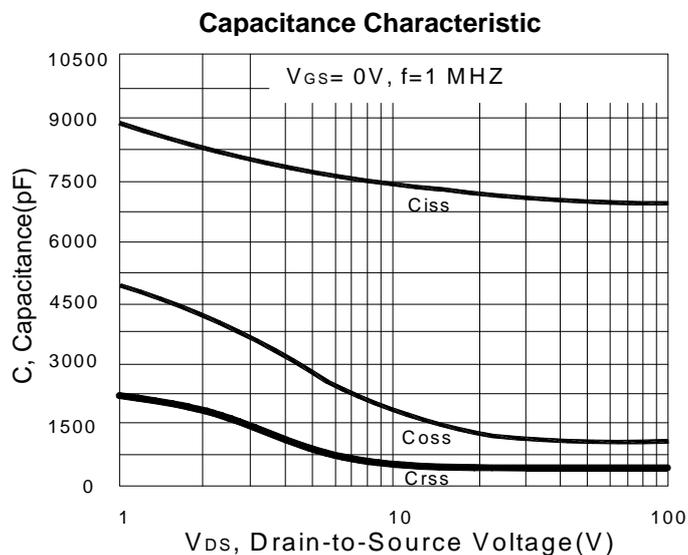
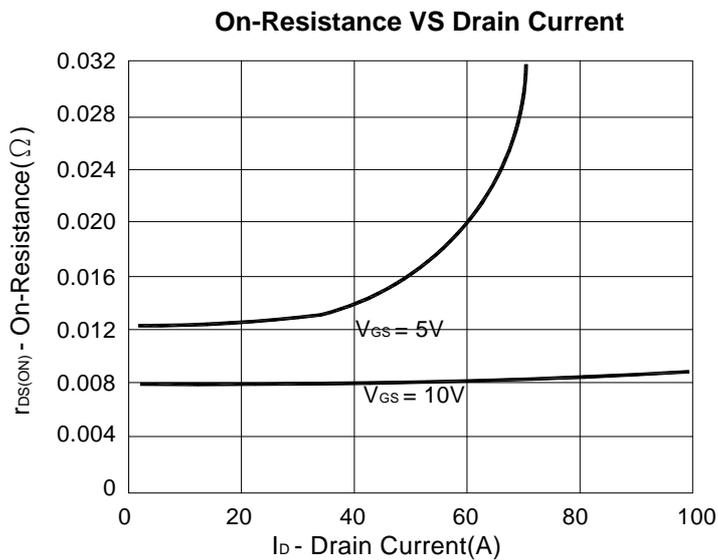
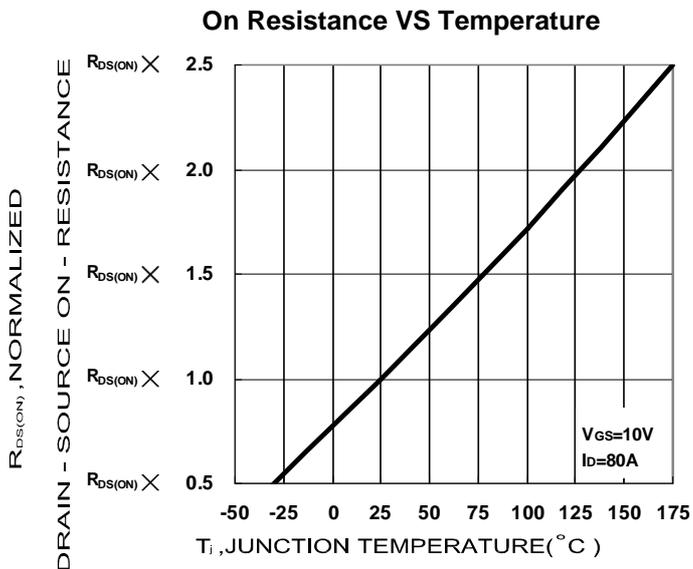
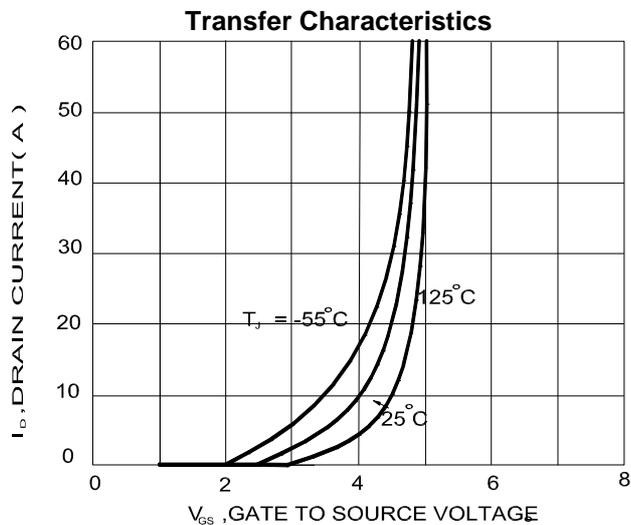
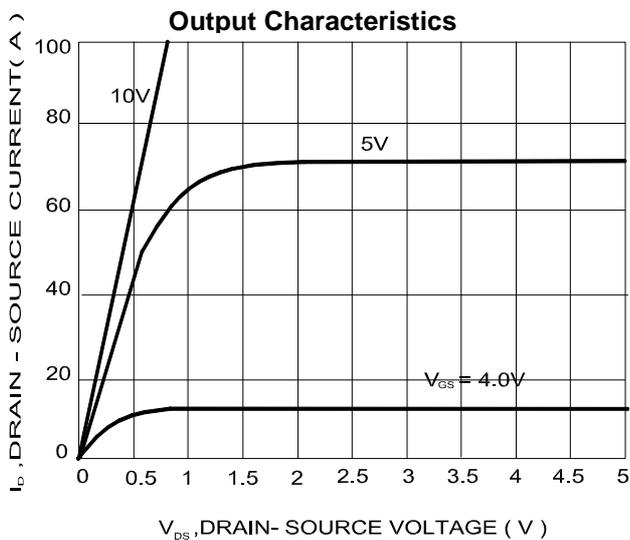
PARAMETER	SYMBOL	TEST CONDITIONS	LIMITS			UNIT
			MIN	TYP	MAX	
STATIC						
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS} = 0V, I_D = 250\mu A$	75			V
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = 250\mu A$	2	2.3	4.0	V
Gate-Body Leakage	I_{GSS}	$V_{DS} = 0V, V_{GS} = \pm 20V$			±250	nA
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS} = 60V, V_{GS} = 0V$			1	μA
		$V_{DS} = 60V, V_{GS} = 0V, T_J = 125\text{ °C}$			10	
On-State Drain Current ¹	$I_{D(ON)}$	$V_{DS} = 10V, V_{GS} = 10V$	85			A
Drain-Source On-State Resistance ¹	$R_{DS(ON)}$	$V_{GS} = 10V, I_D = 80A$		6.5	8	mΩ
Forward Transconductance ¹	g_{fs}	$V_{DS} = 50V, I_D = 80A$		50		S

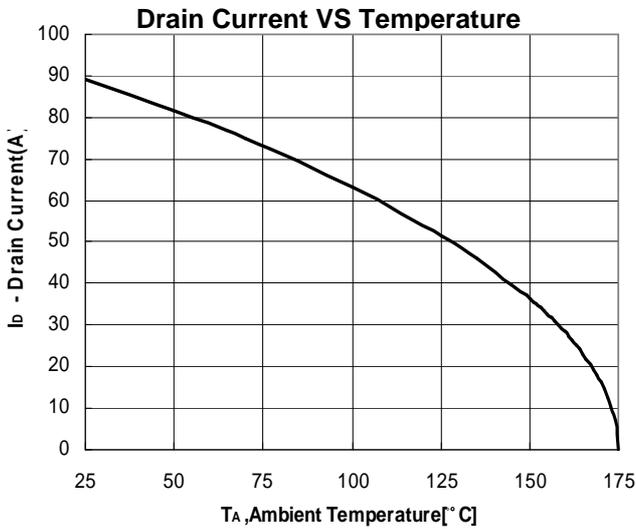
DYNAMIC						
Input Capacitance	C_{iss}	$V_{GS} = 0V, V_{DS} = 25V, f = 1MHz$		7320		pF
Output Capacitance	C_{oss}			980		
Reverse Transfer Capacitance	C_{rss}			404		
Total Gate Charge ²	Q_g	$V_{DS} = 60V, V_{GS} = 10V,$ $I_D = 80A$		129		nC
Gate-Source Charge ²	Q_{gs}			51		
Gate-Drain Charge ²	Q_{gd}			43.5		
Turn-On Delay Time ²	$t_{d(on)}$	$V_{DD} = 40V,$ $I_D \cong 40A, V_{GS} = 10V, R_{GS} = 25\Omega$		54		nS
Rise Time ²	t_r			243		
Turn-Off Delay Time ²	$t_{d(off)}$			297		
Fall Time ²	t_f			166		
SOURCE-DRAIN DIODE RATINGS AND CHARACTERISTICS ($T_J = 25\text{ }^\circ\text{C}$)						
Continuous Current	I_S				89	A
Forward Voltage ¹	V_{SD}	$I_F = 80A, V_{GS} = 0V$			1.3	V
Reverse Recovery Time	t_{rr}	$I_F = 80A, di_F/dt = 100A / \mu S$		120		nS
Reverse Recovery Charge	Q_{rr}			410		nC

¹Pulse test : Pulse Width $\leq 300\ \mu\text{sec}$, Duty Cycle $\leq 2\%$.

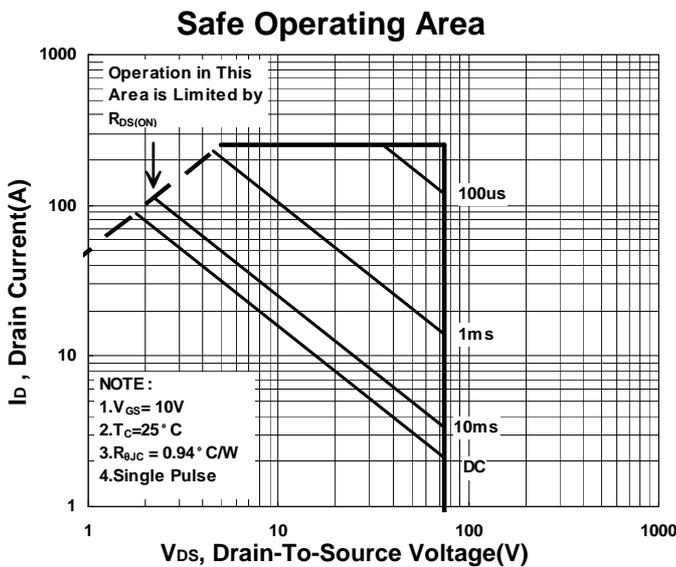
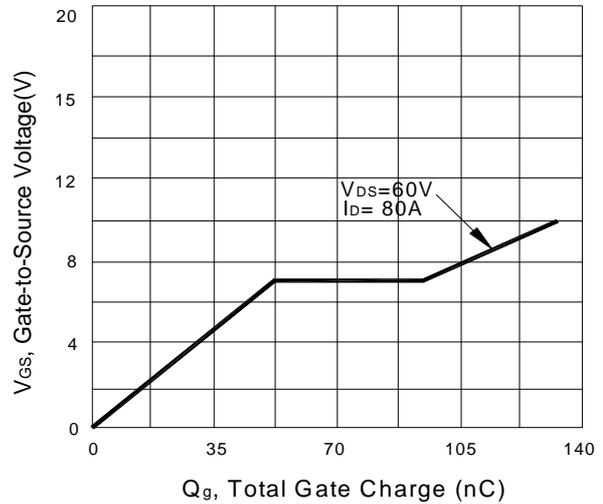
²Independent of operating temperature.

REMARK: THE PRODUCT MARKED WITH "P0808ATG", DATE CODE or LOT #

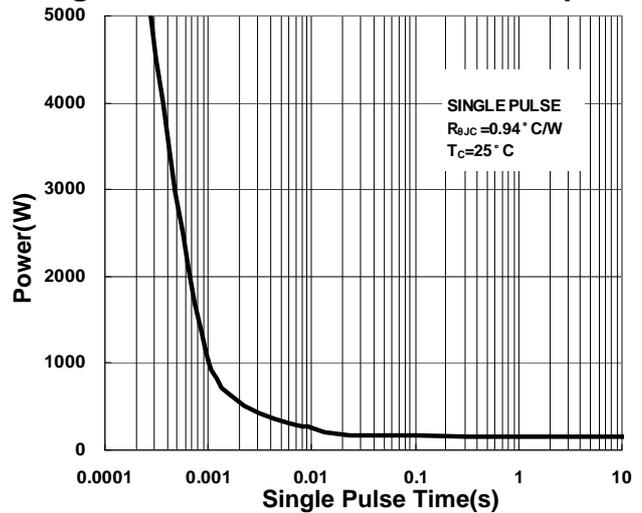




Typical Gate Charge Vs. Gate-to-Source Voltage



Single Pulse Maximum Power Dissipation



Transient Thermal Response Curve

